

ABSTRACT

An undercoat film that prevents copper diffusion and has excellent copper conductor film binding, even when thin. In addition, a material for forming a copper undercoat film, characterized by a compound represented by the general formula: $(R_1R_2)P-(R)_n-Si(X_1X_2X_3)$, wherein at least one of X_1, X_2 and X_3 is a hydrolytic group, R_1 and R_2 are alkyl groups, R denotes a chain-form organic group formed from alkyl groups, aromatic rings or alkyl groups containing aromatic rings, and n is an integer from 1 to 6.